I Claim:

1. A method for producing an optoelectronic component, which comprises:

providing an optoelectronic transducer mounted on a support with inner flat conductors and outer flat conductors;

embedding the transducer and the inner flat conductors in a plastic housing; and

milling the plastic housing to form a radiation-optical functional surface for a coupling partner from a material of the plastic housing.

2. The method according to claim 1, which comprises forming the radiation-optical functional surface in alignment with the transducer.

3. The method according to claim 1, which comprises, prior to the milling step, die-casting an outer enclosure with a guiding stub for the coupling partner onto the plastic housing.

4. The method according to claim 1, which comprises casting the plastic housing with a guiding stub in a mold, with the

guiding stub being separated from the plastic housing by a separating wall.

5. The method according to claim 4, which comprises milling a through-opening into the separating wall.

6. The method according to claim 4, which comprises forming the separating wall during the casting of the plastic housing from a plug, and removing the plug before the milling step.

7. The method according to claim 5, which comprises utilizing a milling head having an outer diameter smaller than an inner diameter of the guiding stub for milling, to form a disk-shaped stop face in the through-opening.

8. The method according to claim 7, which comprises aligning the stop face symmetrically relative to a radiation-optical axis.

9. The method according to claim 7, which comprises setting a spacing distance between a vertex point of the optical functional surface and the stop face to between 10 µm and 100 µm.

10. The method according to claim 9, which comprises setting the spacing distance to between 40 μm and 60 μm.